

**Bump Site Transfer and Qualification of Select 6L and 8L SOT23  
Flip Chip on Lead Packages**

**Automotive Qualification Plan Summary for  
6-SOT\_23 at CARSEM**

<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>EXPECTED COMPLETION DATE</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Sept 2018
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Sept 2018
High Temperature Storage Test (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	Sept 2018
Temperature, Humidity and Bias Test (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	Sept 2018
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	Sept 2018
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	ANSI/ESDA/JEDEC <i>JS-002</i>	3/voltage	Sept 2018

\* These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples will be subjected to wire-pull test after 500 cycles where results should be within specification limits.